General Description

EVALUATION KIT

AVAILABLE

The MAX9994 high-linearity downconversion mixer provides 8.3dB gain, +26.2dBm IIP3, and 9.7dB NF for 1400MHz to 2200MHz UMTS/WCDMA, DCS, and PCS base-station receiver applications. With a wide LO range of 1400MHz to 2000MHz, the MAX9994 can be used in either high-side or low-side LO injection architectures, depending on the RF band of interest. Higher LO applications are supported by the MAX9996, which is pin-pin and functionally compatible with the MAX9994.

In addition to offering excellent linearity and noise performance, the MAX9994 also yields a high level of component integration. This device includes a doublebalanced passive mixer core, an IF amplifier, a dualinput LO selectable switch, and an LO buffer. On-chip baluns are also integrated to allow for single-ended RF and LO inputs. The MAX9994 requires a nominal LO drive of 0dBm, and supply current is guaranteed to be below 235mA.

The MAX9994/MAX9996 are pin compatible with the MAX9984/MAX9986 815MHz to 995MHz mixers, making this entire family of downconverters ideal for applications where a common PC board layout is used for both frequency bands. The MAX9994 is also functionally compatible with the MAX9993.

The MAX9994 is available in a compact, 20-pin, thin QFN package (5mm x 5mm) with an exposed pad. Electrical performance is guaranteed over the extended -40°C to +85°C temperature range.

Applications

UMTS/LTE Base Stations

TD-SCDMA/TD-LTE Base Stations

DCS1800/PCS1900 EDGE Base Stations

cdmaOne[™] and cdma2000[®] Base Stations

PHS/PAS Base Stations

Predistortion Receivers

Fixed Broadband Wireless Access

Wireless Local Loop

Private Mobile Radios

Military Systems

Microwave Links

Digital and Spread-Spectrum Communication Systems

cdma2000 is a registered trademark of Telecommunications Industry Association.

cdmaOne is a trademark of CDMA Development Group.

Features

♦ 1400MHz to 2200MHz RF Frequency Range

- 1400MHz to 2000MHz LO Frequency Range (MAX9994)
- 1900MHz to 2400MHz LO Frequency Range (MAX9996)
- ♦ 40MHz to 350MHz IF Frequency Range
- ♦ 8.3dB Conversion Gain
- +26.2dBm Input IP3
- ♦ +12.6dBm Input 1dB Compression Point
- 9.7dB Noise Figure
- ♦ 67dBc 2RF 2LO Spurious Rejection at $P_{RF} = -10 dBm$
- Integrated LO Buffer
- Integrated RF and LO Baluns for Single-Ended Inputs
- Low -3dBm to +3dBm LO Drive
- Built-In SPDT LO Switch with 45dB LO1 to LO2 Isolation and 50ns Switching Time
- Pin Compatible with the MAX9984/MAX9986 815MHz to 995MHz Mixers
- Functionally Compatible with the MAX9993
- External Current-Setting Resistors Provide Option for Operating Mixer in Reduced Power/Reduced **Performance Mode**

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX9994ETP+	-40°C to +85°C	20 Thin QFN-EP** 5mm × 5mm bulk
MAX9994ETP+T	-40°C to +85°C	20 Thin QFN-EP** 5mm × 5mm T/R

**EP = Exposed pad.

+Denotes a lead(Pb)-free/RoHS-compliant package. T = Tape and reel.

Pin Configuration/Functional Diagram and Typical Application Circuit appear at end of data sheet.

Maxim Integrated Products 1

MAX9994

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND0.3V to +5.5V
IF+, IF-, LOBIAS, LOSEL, IFBIAS to GND0.3V to (V _{CC} + 0.3V)
TAP0.3V to +1.4V
LO1, LO2, LEXT to GND0.3V to +0.3V
RF, LO1, LO2 Input Power+12dBm
RF (RF is DC shorted to GND through a balun)50mA
Continuous Power Dissipation ($T_A = +70^{\circ}C$)
20-Pin Thin QFN-EP (derate 20mW/°C above +70°C)1.8W

θJA (Note 1)	+38°C/W
θJC (Note 1)	+8°C/W
Operating Temperature Range (Note 2)	$T_{\rm C} = -40^{\circ}{\rm C}$ to $+85^{\circ}{\rm C}$
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering 10s)	+300°C
Soldering Temperature (reflow)	+260°C

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <u>www.maxim-ic.com/thermal-tutorial</u>.
Note 2: T_C is the temperature on the exposed pad of the package.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

(*Typical Application Circuit*, V_{CC} = +4.75V to +5.25V, no RF signal applied, IF+ and IF- outputs pulled up to V_{CC} through inductive chokes, R_1 = 806 Ω , R_2 = 549 Ω , T_C = -40°C to +85°C, unless otherwise noted. Typical values are at V_{CC} = +5V, T_C = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Supply Voltage	V _{CC}		4.75	5.00	5.25	V
Supply Current	Icc			206	235	mA
LO_SEL Input Logic-Low	VIL				0.8	V
LO_SEL Input Logic-High	VIH		2			V

RECOMMENDED AC OPERATING CONDITIONS

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
RF Frequency Range	f _{RF}	(Note 3)	1400		2200	MHz
LO Frequency Range	fLO	(Note 3)	1400		2000	MHz
IF Frequency Range	fIF	(Note 3)	40		350	MHz
LO Drive Level	PLO	(Note 3)	-3		+3	dBm

AC ELECTRICAL CHARACTERISTICS-fRF = 1700MHz TO 2200MHz, LOW-SIDE LO INJECTION

(*Typical Application Circuit*, V_{CC} = +4.75V to +5.25V, RF and LO ports are driven from 50 Ω sources, P_{LO} = -3dBm to +3dBm, P_{RF} = -5dBm, f_{RF} = 1700MHz to 2200MHz, f_{LO} = 1400MHz to 2000MHz, f_{IF} = 200MHz, f_{RF} > f_{LO}, T_C = -40°C to +85°C, unless otherwise noted. Typical values are at V_{CC} = +5V, P_{RF} = -5dBm, P_{LO} = 0dBm, f_{RF} = 1900MHz, f_{LO} = 1700MHz, f_{IF} = 200MHz, T_C = +25°C, unless otherwise noted.) (Notes 4, 5)

PARAMETER	SYMBOL	CONE	DITIONS	MIN	ТҮР	MAX	UNITS
Conversion Gain	GC	$P_{RF} < +2dBm, T_{A} = 1$	+25°C (Note 6)	7.2	8.3	9.2	dB
Gain Variation Over Temperature		$T_{\rm C} = -40^{\circ}{\rm C} \text{ to } +85^{\circ}{\rm C}$			±0.75		dB
Input Compression Point	P _{1dB}	(Note 7)	(Note 7)		12.6		dBm
Input Third-Order Intercept Point (Note 6)	IIP3	Two tones: $f_{RF1} = 2000MHz$, $f_{RF2} = 2001MHz$, $P_{RF} = -5dBm/tone$, $f_{LO} = 1800MHz$, $P_{LO} = 0dBm$, $T_A = +25^{\circ}C$		23.5	26.2		dBm
Input IP3 Variation Over Temperature		$T_{\rm C} = -40^{\circ}{\rm C} \text{ to } +85^{\circ}{\rm C}$	$T_{\rm C}$ = -40°C to +85°C		±0.5		dB
Noise Figure	NF	Single sideband			9.7		dB
Noise Figure Under-Blocking		$P_{RF} = 5dBm, f_{RF} = 2000MHz,$ $f_{LO} = 1810MHz, f_{block} = 2100MHz (Note 8)$			19		dB
LO Drive				-3		+3	dBm
	00		$P_{RF} = -10 dBm$		67		
	2 x 2	2RF - 2LO	P _{RF} = -5dBm		62		dBc
Spurious Response at IF		$ \begin{array}{c} x \ 3 \end{array} \begin{array}{c} \text{P}_{\text{RF}} = -10 \text{dBm} \\ \text{P}_{\text{RF}} = -5 \text{dBm} \end{array} \end{array} $	$P_{RF} = -10 dBm$		82		
	3 X 3			72]	
LO1 to LO2 Isolation		LO2 selected, 1500MHz < f _{LO} < 1700MHz		40	52		٩D
(Note 4)		LO1 selected, 1500MHz < f _{LO} < 17	'00MHz	40	45		dB
Maximum LO Leakage at RF Port		$P_{LO} = +3dBm$			-17		dBm
Maximum LO Leakage at IF Port		$P_{LO} = +3dBm$			-30		dBm
Minimum RF-to-IF Isolation					35		dB
LO Switching Time		50% of LOSEL to IF s	settled to within 2°		50		ns
RF Port Return Loss					21		dB
			LO1/2 port selected, LO2/1 and IF terminated		16		dD
LO Port Return Loss		LO1/2 port unselecte LO2/1 and IF termina			26		dB
IF Port Return Loss		LO driven at 0dBm, F 50 Ω , differential 200			20		dB

AC ELECTRICAL CHARACTERISTICS—fRF = 1455MHz, HIGH-SIDE LO INJECTION

(*Typical Application Circuit*, RF and LO ports are driven from 50 Ω sources, f_{RF} < f_{LO}, V_{CC} = +5V, P_{RF} = -5dBm, P_{LO} = 0dBm, f_{RF} = 1455MHz, f_{LO} = 1625MHz, f_{IF} = 170MHz, T_C = +25°C, LO2 is selected, unless otherwise noted.) (Note 5)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Conversion Gain	GC			8.8		dB
Input Third-Order Intercept Point	IIP3	Two tones: $f_{RF1} = 1455MHz$, $f_{RF2} = 1456MHz$, $P_{RF} = -5dBm/tone$		25.6		dBm
Input Compression Point (Note 7)	IP _{1dB}			12.7		dBm
2LO - 2RF Spurious Response	2 x 2	P _{RF} = -10dBm		71.4		dBc
2LO - Zhi Spullous hespolise	2 X Z	P _{RF} = -5dBm		66.4		UBC
LO-to-IF Leakage		LOSEL = LO2		-30.2		dBm

AC ELECTRICAL CHARACTERISTICS—f_{RF} = 1500MHz, HIGH-SIDE LO INJECTION

(*Typical Application Circuit*, RF and LO ports are driven from 50Ω sources, f_{RF} < f_{LO}, V_{CC} = +5V, P_{RF} = -5dBm, P_{LO} = 0dBm, f_{RF} = 1500MHz, f_{LO} = 1650MHz, f_{IF} = 150MHz, T_C = +25°C, LO1 is selected, unless otherwise noted.) (Note 5)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
Conversion Gain	GC			8.9		dB
Input Third-Order Intercept Point	IIP3	Two tones: $f_{RF1} = 1500MHz$, $f_{RF2} = 1501MHz$, $P_{RF} = -5dBm/tone$		25.5		dBm
Input Compression Point (Note 7)	IP _{1dB}			12.5		dBm
2LO - 2RF Spurious Response	2 x 2	P _{RF} = -10dBm		70.4		dBc
	2 X Z	P _{RF} = -5dBm		65.4		
LO-to-IF Leakage				-33.2		dBm

Note 3: Operation outside this range is possible, but with degraded performance of some parameters.

Note 4: Guaranteed by design and characterization.

Note 5: All limits include external component losses. Output measurements taken at IF output of the Typical Application Circuit.

Note 6: Production tested.

Note 7: Compression point characterized. It is advisable not to operate continuously the mixer RF input above +12dBm.

Note 8: Measured with external LO source noise filtered so the noise floor is -174dBm/Hz. This specification reflects the effects of all SNR degradations in the mixer, including the LO noise as defined in Application Note 2021: Specifications and Measurement of Local Oscillator Noise in Integrated Circuit Base Station Mixers.

 $P_{LO} = -3dBm, 0dBm, +3dBm$

1800 1950 2100

RF FREQUENCY (MHz)

2250 2400

10

9

8

7

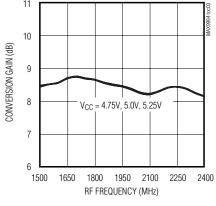
6

1500

1650

CONVERSION GAIN (dB)

Typical Operating Characteristics (MAX9994 Typical Application Circuit, VCC = +5.0V, PLO = 0dBm, PRF = -5dBm, fRF = 1700MHz to 2200MHz, LO is Low-Side Injected for a 200MHz IF, unless otherwise noted.) **CONVERSION GAIN vs. RF FREQUENCY CONVERSION GAIN vs. RF FREQUENCY CONVERSION GAIN vs. RF FREQUENCY** 11 11



INPUT IP3 vs. RF FREQUENCY

1800 1950 2100 RF FREQUENCY (MHz)

 $T_C = +25^{\circ}C$

2250 2400

11

10

9

8

7

6

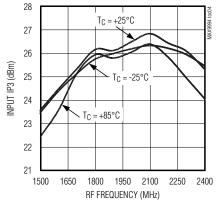
1500

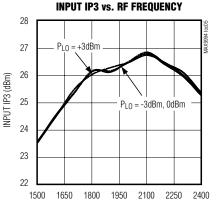
CONVERSION GAIN (dB)

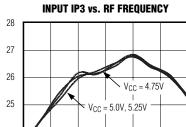
 $T_{\rm C} = -25^{\circ}{\rm C}$

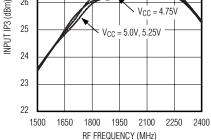
T_C = +85°C

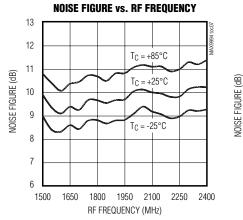
1650





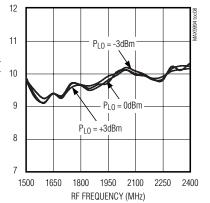


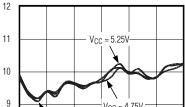




NOISE FIGURE vs. RF FREQUENCY

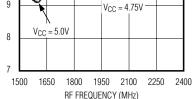
RF FREQUENCY (MHz)





VOISE FIGURE (dB)

NOISE FIGURE vs. RF FREQUENCY



MAX9994

MIXIM

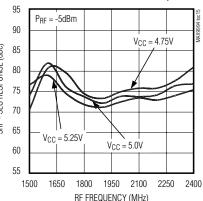
(MAX9994 Typical Application Circuit, VCC = +5.0V, PLO = 0dBm, PRF = -5dBm, fRF = 1700MHz to 2200MHz, LO is Low-Side



Injected for a 200MHz IF, unless otherwise noted.) **2RF - 2LO RESPONSE vs. RF FREQUENCY 2RF - 2LO RESPONSE vs. RF FREQUENCY 2RF - 2LO RESPONSE vs. RF FREQUENCY** 85 85 90 $P_{RF} = -5 dBm$ $P_{RF} = -5 dBm$ $P_{RF} = -5dBm$ 80 85 80 80 2L0 RESPONSE (dBc) 75 - 2L0 RESPONSE (dBc) $P_{L0} = +3dBm$ (dBc) 75 75 **2LO RESPONSE** 70 T_C = +25°C -70 70 _T_C = -25°C 65 65 65 60 60 60 2RF 2RF . 2RF $P_{L0} = 0 dBm$ 55 55 55 T_C = +85°C V_{CC} = 4.75V, 5.0V, 5.25V 50 $P_{L0} = -3dBm$ 50 50 45 45 45 1500 1650 1800 1950 2100 2250 2400 1500 1650 1800 1950 2100 2400 1500 1650 1800 1950 2100 2250 2250 RF FREQUENCY (MHz) RF FREQUENCY (MHz) RE FREQUENCY (MHz) **3RF - 3LO RESPONSE vs. RF FREQUENCY 3RF - 3LO RESPONSE vs. RF FREQUENCY 3RF - 3LO RESPONSE vs. RF FREQUENCY** 95 95 95 $P_{RF} = -5 dBm$ $P_{RF} = -5 dBm$ $P_{RF} = -5 dBm$ 90 90 90 T_C = +85°C 3L0 RESPONSE (dBc) 85 85 **3L0 RESPONSE (dBc)** 85 **3LO RESPONSE (dBc)** 80 80 80 75 75 75 70 70 70 $P_{LO} = -3dBm, 0dBm, +3dBm$ 3RF 3RF 3RF 65 65 65 $T_C = -25^{\circ}C$ $V_{CC} = 5.25V$ $T_C = +25^{\circ}C$ $V_{CC} = 5.0V$ 60 60 60 55 55 55 1650 1800 1950 2100 2250 2400 1650 1800 1950 2100 2250 2400 1650 1500 1500 1500 1800 1950 2100 RF FREQUENCY (MHz) RF FREQUENCY (MHz) RF FREQUENCY (MHz) **INPUT P1dB vs. RF FREQUENCY INPUT P1dB vs. RF FREQUENCY INPUT P1dB vs. RF FREQUENCY** 15 15 15 $V_{CC} = 5.25V$ 14 +85°C 14 14 Tc INPUT P_{1dB} (dBm) INPUT P1dB (dBm) NPUT P1dB (dBm) 13 13 13 12 12 12 $T_{C} =$ -25°C PLO = -3dBm, 0dBm, +3dBm $V_{CC} = 5.0V$ $T_C = +25^{\circ}C$ $V_{CC} = 4.75V$ 11 11 11 10 10 10 2400 2400 1500 1650 1800 1950 2100 2250 1500 1650 1800 1950 2100 2250 1500 1650 1800 1950 2100 2250 RF FREQUENCY (MHz) RF FREQUENCY (MHz) RF FREQUENCY (MHz)

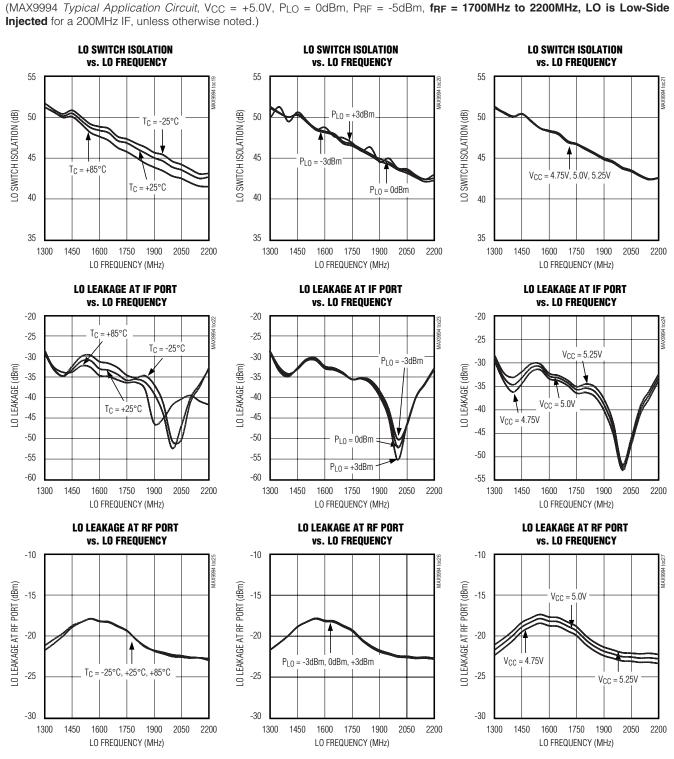
2400

Typical Operating Characteristics (continued)



2400

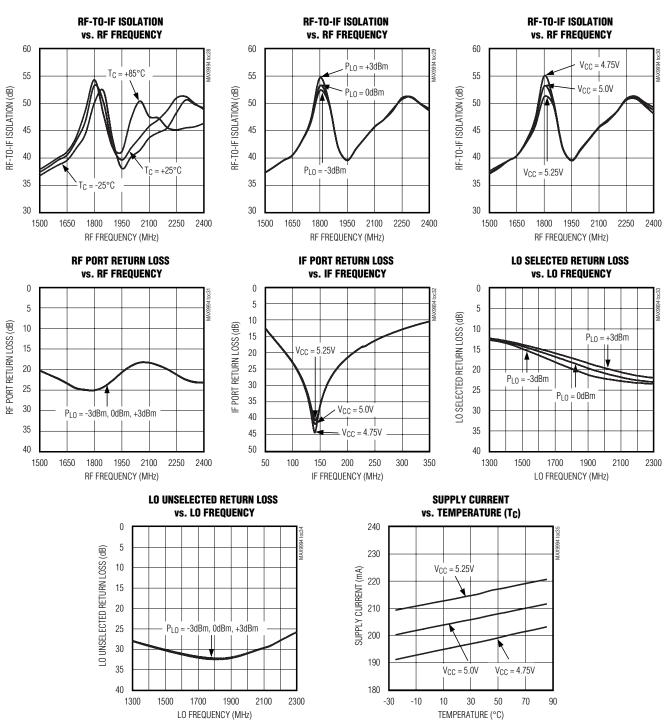
Typical Operating Characteristics (continued)



7

MAX9994



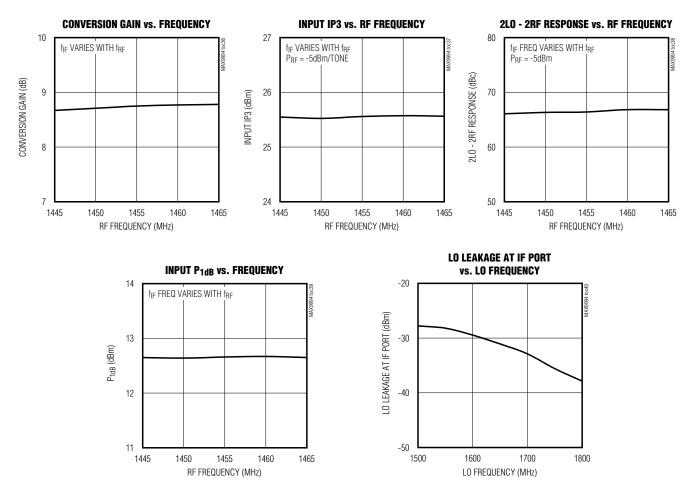


Typical Operating Characteristics (continued)

(MAX9994 *Typical Application Circuit*, $V_{CC} = +5.0V$, $P_{LO} = 0dBm$, $P_{RF} = -5dBm$, $f_{RF} = 1700MHz$ to 2200MHz, LO is Low-Side Injected for a 200MHz IF, unless otherwise noted.)

Typical Operating Characteristics (continued)

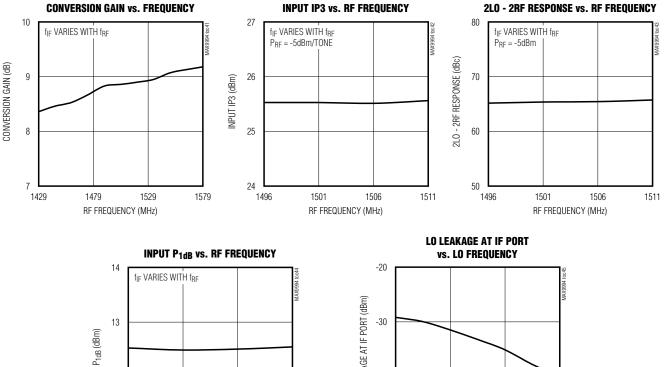
(MAX9994 *Typical Application Circuit*, V_{CC} = +5V, P_{LO} = 0dBm, LO2 selected, P_{RF} = -5dBm, **f_{RF} = 1400MHz to 1700MHz, LO is High-Side Injected** for a 170MHz IF, unless otherwise noted.)

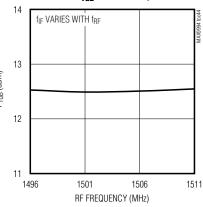


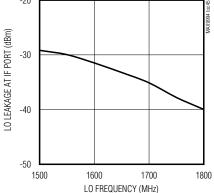
MAX9994



(MAX9994 Typical Application Circuit, VCC = +5V, PLO = 0dBm, LO1 selected, PRF = -5dBm, fRF = 1400MHz to 1700MHz, LO is High-Side Injected for a 150MHz IF, unless otherwise noted.)







Pin Description

MAX9994

PIN	NAME	FUNCTION
1, 6, 8, 14	Vcc	Power-Supply Connection. Bypass each V _{CC} pin to GND with capacitors as shown in the <i>Typical</i> Application Circuit.
2	RF	Single-Ended 50 Ω RF Input. This port is internally matched and DC shorted to GND through a balun. Requires an external DC-blocking capacitor.
3	TAP	Center Tap of the Internal RF Balun. Bypass to GND with capacitors close to the IC, as shown in the <i>Typical Application Circuit</i> .
4, 5, 10, 12, 13, 17	GND	Ground
7	LOBIAS	Bias Resistor for Internal LO Buffer. Connect a 549 Ω ±1% resistor from LOBIAS to the power supply.
9	LOSEL	Local Oscillator Select. Logic control input for selecting LO1 or LO2.
11	LO1	Local Oscillator Input 1. Drive LOSEL low to select LO1.
15	LO2	Local Oscillator Input 2. Drive LOSEL high to select LO2.
16	LEXT	External Inductor Connection. Connect a low-ESR, 10nH inductor from LEXT to GND. This inductor carries approximately 100mA DC current.
18, 19	IF-, IF+	Differential IF Outputs. Each output requires external bias to V _{CC} through an RF choke (see the <i>Typical Application Circuit</i>).
20	IFBIAS	IF Bias Resistor Connection for IF Amplifier. Connect an 806Ω resistor from IFBIAS to GND.
_	EP	Exposed Pad. Solder the exposed pad to the ground plane using multiple vias.

Detailed Description

The MAX9994 high-linearity downconversion mixer provides 8.3dB of conversion gain and 26.2dBm of IIP3, with a typical 9.7dB noise figure. The integrated baluns and matching circuitry allow for 50Ω single-ended interfaces to the RF and the two LO ports. A single-pole, double-throw (SPDT) switch provides 50ns switching time between the two LO inputs with 45dB of LO-to-LO isolation. Furthermore, the integrated LO buffer provides a high drive level to the mixer core, reducing the LO drive required at the MAX9994's inputs to a range of -3dBm to +3dBm. The IF port incorporates a differential output, which is ideal for providing enhanced IIP2 performance.

Specifications are guaranteed over broad frequency ranges to allow for use in WCDMA, TD-SCDMA, LTE, TD-LTE, cdma2000, and 2G/2.5G/3G DCS1800 and PCS1900 base stations. The MAX9994 is specified to operate over a 1400MHz to 2200MHz RF frequency range, a 1400MHz to 2000MHz LO frequency range, and a 40MHz to 350MHz IF frequency range. Operation beyond these ranges is possible; see the *Typical Operating Characteristics* for additional details.

With a wide LO range of 1400MHz to 2000MHz, the MAX9994 can be used in either high-side or low-side LO injection architectures, depending on the RF band of interest. Higher LO applications are supported by the MAX9996, which is pin-pin and functionally compatible with the MAX9994.

RF Input and Balun

The MAX9994 RF input is internally matched to 50Ω , requiring no external matching components. A DCblocking capacitor is required because the input is internally DC shorted to ground through the on-chip balun. Input return loss is typically 21dB over the entire 1700MHz to 2200MHz RF frequency range.

LO Inputs, Buffer, and Balun

The MAX9994 can be used for either high-side or lowside injection applications with a 1400MHz to 2000MHz LO frequency range. For a device with a 1900MHz to 2400MHz LO frequency range, refer to the MAX9996 data sheet. As an added feature, the MAX9994 includes an internal LO SPDT switch that can be used for frequency-hopping applications. The switch selects one of the two single-ended LO ports, allowing the external oscillator to settle on a particular frequency before it is



switched in. LO switching time is typically less than 50ns, which is more than adequate for virtually all GSM applications. If frequency hopping is not employed, set the switch to either of the LO inputs. The switch is controlled by a digital input (LOSEL): logic-high selects LO2, logic-low selects LO1. LO1 and LO2 inputs are internally matched to 50Ω , requiring only a 22pF DC blocking capacitor.

A two-stage internal LO buffer allows a wide input power range for the LO drive. All guaranteed specifications are for an LO signal power from -3dBm to +3dBm. The on-chip low-loss balun, along with an LO buffer, drives the double-balanced mixer. All interfacing and matching components from the LO inputs to the IF outputs are integrated on-chip.

High-Linearity Mixer

The core of the MAX9994 is a double-balanced, highperformance passive mixer. Exceptional linearity is provided by the large LO swing from the on-chip LO buffer. When combined with the integrated IF amplifiers, the cascaded IIP3, 2RF - 2LO rejection, and NF performance is typically 26.2dBm, 67dBc, and 9.7dB, respectively.

Differential IF Output Amplifier

The MAX9994 mixer has a 40MHz to 350MHz IF frequency range. The differential, open-collector IF output ports require external pullup inductors to V_{CC}. Note that these differential outputs are ideal for providing enhanced 2RF - 2LO rejection performance. Single-ended IF applications require a 4:1 balun to transform the 200 Ω differential output impedance to a 50 Ω single-ended output. After the balun, the IF return loss is better than 15dB.

Applications Information

Input and Output Matching

The RF and LO inputs are internally matched to 50Ω . No matching components are required. Return loss at the RF port is typically 21dB over the 1700MHz to 2200MHz input range, and the return loss at the LO port is typically better than 14dB (1400MHz to 2000MHz). RF and LO inputs require only DC-blocking capacitors for interfacing.

The IF output impedance is 200Ω (differential). For evaluation, an external low-loss 4:1 (impedance ratio) balun transforms this impedance down to a 50Ω single-ended output (see the *Typical Application Circuit*).

Bias Resistors

Bias currents for the LO buffer and the IF amplifier are optimized by fine tuning resistors R1 and R2. If reduced current is required at the expense of performance, contact the factory for details. If the $\pm 1\%$ bias resistor values are not readily available, substitute standard $\pm 5\%$ values.

LEXT Inductor

Short LEXT to ground using a 0Ω resistor. For applications requiring improved RF-to-IF and LO-to-IF isolation, a 10nH inductor (L3) can be used in place of the 0Ω resistor. However, in order to ensure stable operation, the mixer IF ports must be presented with a low common-mode load impedance. Contact the factory for details. Since approximately 100mA flows through LEXT, it is important to use a low-DCR wire-wound inductor.

Layout Considerations

A properly designed PC board is an essential part of any RF/microwave circuit. Keep RF signal lines as short as possible to reduce losses, radiation, and inductance. For the best performance, route the ground pin traces directly to the exposed pad under the package. The PC board exposed pad **MUST** be connected to the ground plane of the PC board. It is suggested that multiple vias be used to connect this pad to the lower level ground planes. This method provides a good RF/thermal conduction path for the device. Solder the exposed pad on the bottom of the device package to the PC board. The MAX9994 evaluation kit can be used as a reference for board layout. Gerber files are available upon request at **www.maxim-ic.com**.

Power-Supply Bypassing

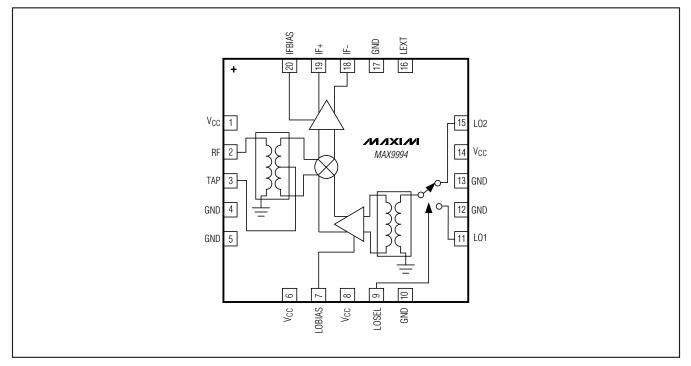
Proper voltage-supply bypassing is essential for highfrequency circuit stability. Bypass each V_{CC} pin and TAP with the capacitors shown in the *Typical Application Circuit*; see Table 1. Place the TAP bypass capacitor to ground within 100 mils of the TAP pin.

Exposed Pad RF/Thermal Considerations The exposed pad (EP) of the MAX9994's 20-pin thin QFN-EP package provides a low thermal-resistance path to the die. It is important that the PCB on which the MAX9994 is mounted be designed to conduct heat from the EP. In addition, provide the EP with a lowinductance path to electrical ground. The EP **MUST** be soldered to a ground plane on the PCB, either directly or through an array of plated via holes.

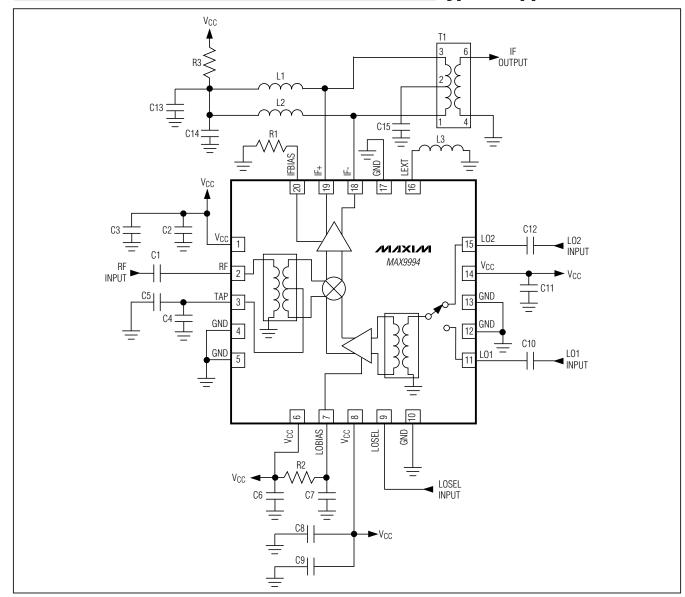
Table 1. Component List Referring to the Typical Application Circuit

COMPONENT	VALUE	DESCRIPTION
C1	4pF	Microwave capacitor (0603)
C2, C6, C7, C8, C10, C12	22pF	Microwave capacitors (0603)
C3, C5, C9, C11	0.01µF	Microwave capacitors (0603)
C4	10pF	Microwave capacitor (0603)
C13, C14	150pF	Microwave capacitors (0603)
C15	150pF	Microwave capacitor (0402)
L1, L2	470nH	Wire-wound high-Q inductors (0805)
L3	10nH	Wire-wound high-Q inductor (0603)
R1	806Ω	±1% resistor (0603)
R2	549Ω	±1% resistor (0603)
R3	7.15Ω	±1% resistor (1206)
T1	4:1 balun	IF balun
U1	MAX9994	Maxim IC

Pin Configuration/Functional Diagram



Typical Application Circuit



_Chip Information

PROCESS: SiGe BiCMOS

Package Information

For the latest package outline information and land patterns, go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
20 TQFN-EP	T2055+3	<u>21-0140</u>	<u>90-008</u>

MAX9994

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	10/04	Initial release	—
1	12/10	Updated Title, General Description, Ordering Information, Absolute Maximum Ratings, Electrical Characteristics, Typical Operating Characteristics, Pin Description, General Description, and Applications Information sections	1–12

MAX9994

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600 ___

_____ 15

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Up-Down Converters category:

Click to view products by Maxim manufacturer:

Other Similar products are found below :

HMC7586-SX HMC7587 HMC8119-SX HMC7587-SX HMC6147ALC5ATR MDS-158-PIN LA8153QA-WH HMC7912LP5ETR HMC377QS16GETR MY87C CSM2-10 CHR3762-QDG AD6620ASZ-REEL ADF5904ACPZ ADF5904WCCPZ AD6623ASZ AD6633BBCZ AD6634BBCZ AD9957BSVZ AD9957BSVZ-REEL ADMV1009AEZ ADMV1010AEZ ADMV1011AEZ ADMV1012AEZ ADRF6658BCPZ HMC951ALP4E HMC1190ALP6NE HMC571 HMC6146BLC5A HMC6146BLC5ATR HMC571LC5 HMC572LC5 HMC925LC5 HMC6787ALC5A HMC6787ALC5ATR HMC683LP6CE HMC682LP6CE HMC571LC5TR HMC7911LP5E HMC7912LP5E HMC908ALC5 HMC966LP4E HMC967LP4E HMC977LP4E AD6634BBC HMC6505ALC5 MAUC-011003-TR0500 MAX19996AETP+ MAX2039ETP+ MAX2410EEI+